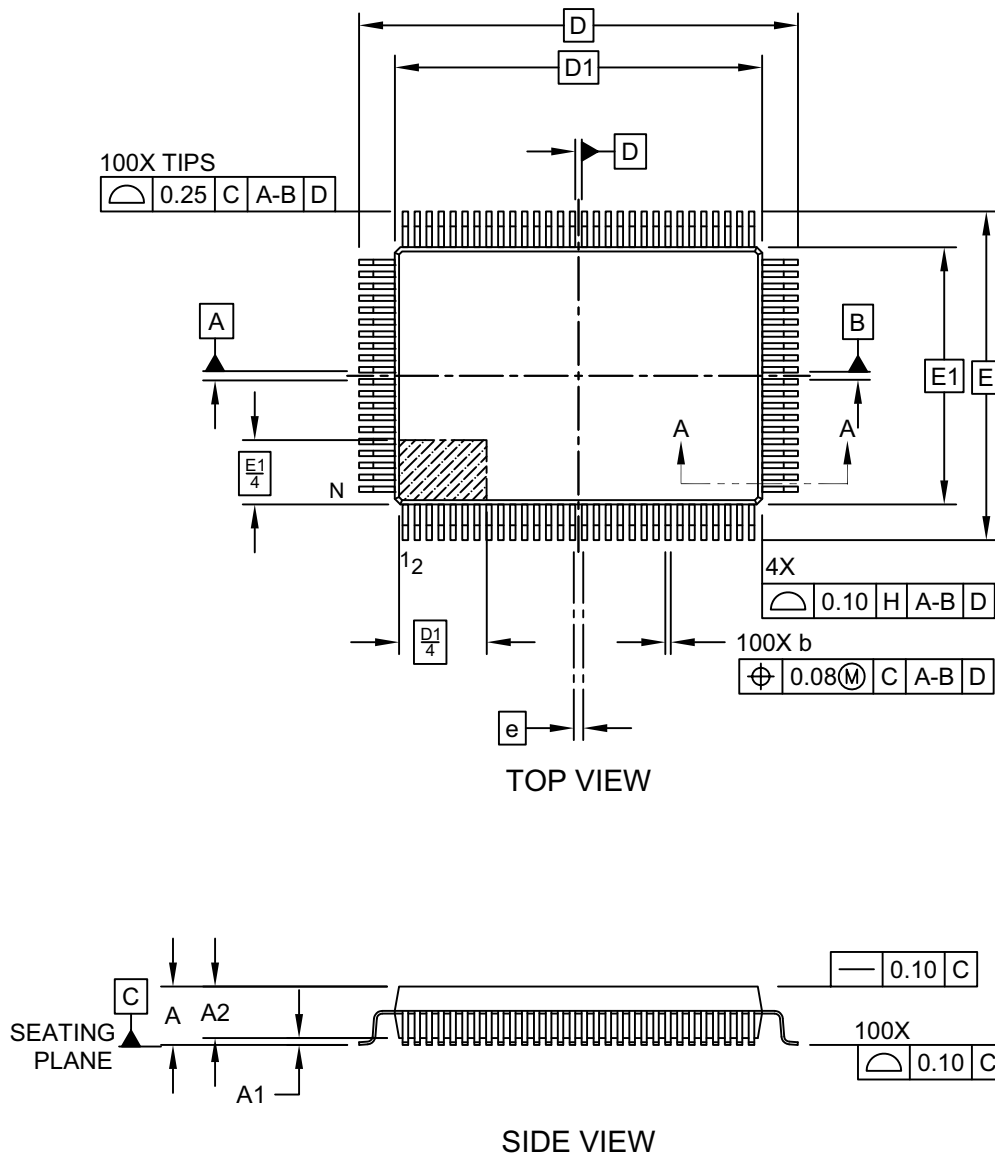


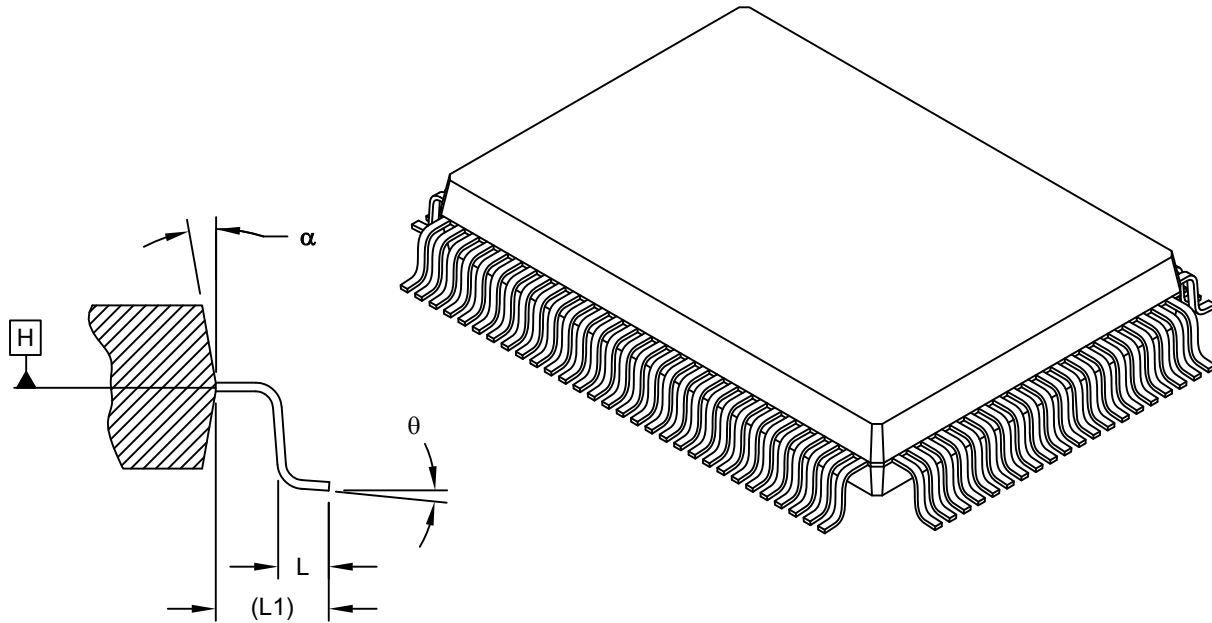
100-Lead Metric Plastic Quad Flat Pack (TSX) - 14x20 mm Body [QFP]
With 3.9 mm Foot Print; SMSC Legacy Package

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



100-Lead Metric Plastic Quad Flat Pack (TSX) - 14x20 mm Body [QFP] With 3.9 mm Foot Print; SMSC Legacy Package

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SECTION A-A

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Leads	N	100		
Lead Pitch	e	0.65 BSC		
Overall Height	A	-	-	3.40
Standoff	A1	0.05	-	0.50
Molded Package Thickness	A2	2.55	-	3.05
Foot Length	L	0.73	0.88	1.03
Footprint	L1	1.95 REF		
Foot Angle	θ	0°	3.5°	7°
Overall Length	D	23.90 BSC		
Overall Width	E	17.90 BSC		
Molded Package Length	D1	20.00 BSC		
Molded Package Width	E1	14.00 BSC		
Lead Width	b	0.20	-	0.40
Mold Draft Angle Top	α	5°	-	16°

Notes:

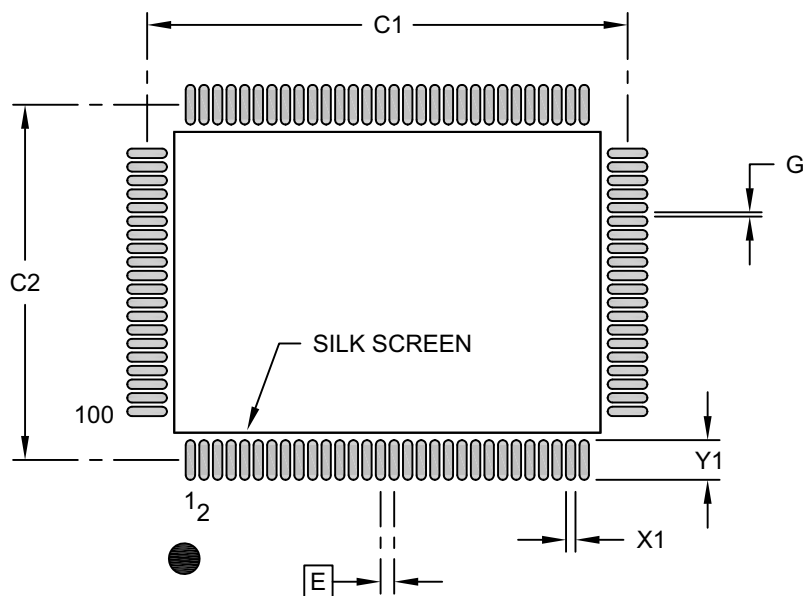
- Pin 1 visual index feature may vary, but must be located within the hatched area.
- Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

100-Lead Metric Plastic Quad Flat Pack (TSX) - 14x20 mm Body [QFP] With 3.9 mm Foot Print; SMSC Legacy Package

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	0.65 BSC		
Contact Pad Spacing	C1		23.00	
Contact Pad Spacing	C2		17.00	
Contact Pad Width (X100)	X1			0.45
Contact Pad Length (X100)	Y1			1.90
Contact Pad to Center Pad (X96)	G	0.20		

Notes:

- Dimensioning and tolerancing per ASME Y14.5M
BSC: Basic Dimension. Theoretically exact value shown without tolerances.